

Electronic Modules and Packaging Solutions

APPLICATIONS:

Sensor Housings

RF, Hybrid, Converters & Solar Devices

UV and Light Detectors

RFID & Security Tags

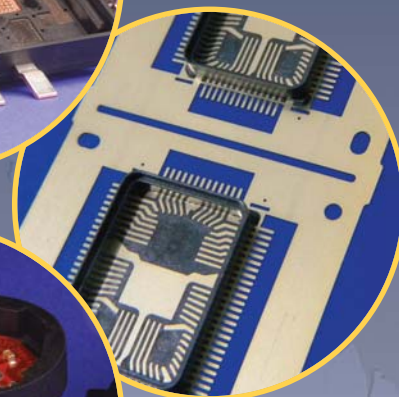
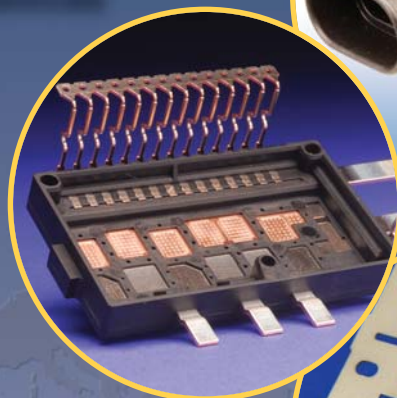
Tire Pressure Housings

Component Holders

Ceramic Interconnects

Microelectronics

Semiconductor Packages



Automotive



Mil-Aero/Industrial



Consumer Electronics



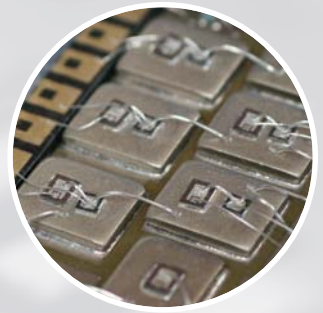
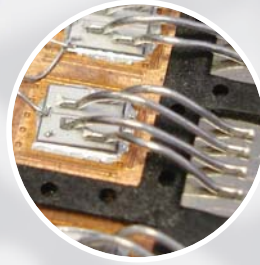
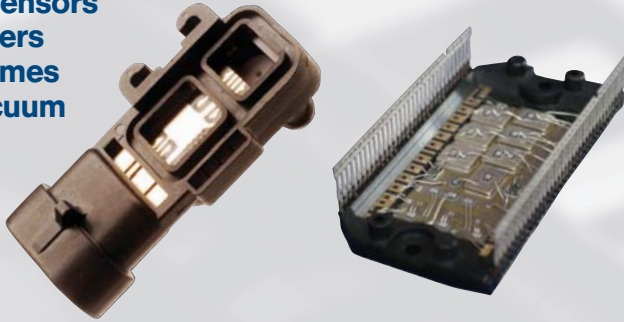
Medical

TM
Interplex
Industries, Inc.

Global Solutions for Complex Parts and Assemblies

Die & Wire-Bondable Electronic Packages

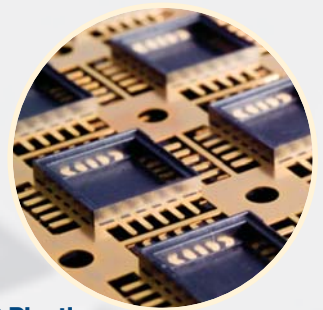
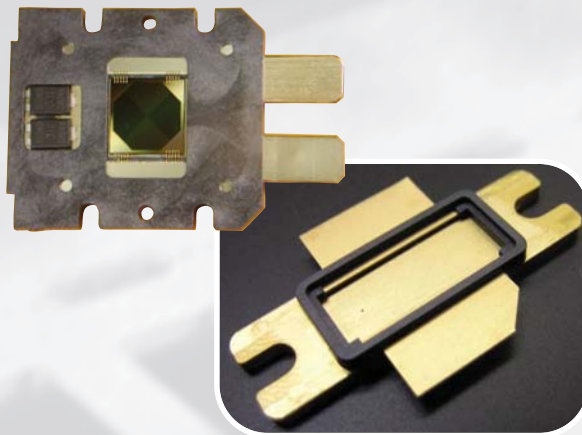
Sensor Connector Housings
Power Electronics
Temperature Sensors
Motor Controllers
Power Leadframes
Pressure & Vacuum



- Wire-bondable Ag, Ni, Pd, Au, NiP Platings
- Metal or Plastic Die Paddles
- Reel to Reel options
- Ductile Thermal Heat Spreaders

Semiconductor Packages

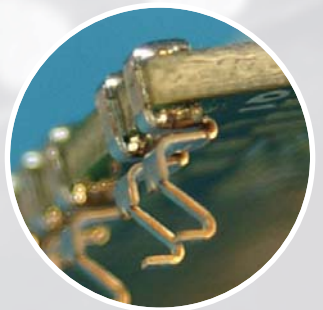
MEMS
CPV Solar
Pressure & Motion
RF Power
UV Detectors
LED
Multi-Chip
High Power
Photonic



- High Temperature LCP Plastic
- Metal or Plastic Die Paddle
- Reel to Reel
- Wire-bondable
- Copper Base Flange Technology
- SMT, Through-Hole

Solder Bearing Interconnect Products

Microelectronics
Multichip Modules
Memory Modules
Ceramic Interconnects
Sensor Assemblies



- Large Variety of Solder Types
- CTE Mismatch Compliant
- Reel to Reel for Automation
- Zip, SIP, Zig-Zag Configurations
- Connectors

PCB Interface, Press-Fit and Bondable Packages

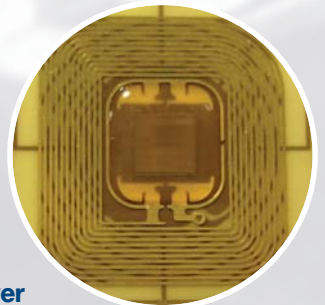
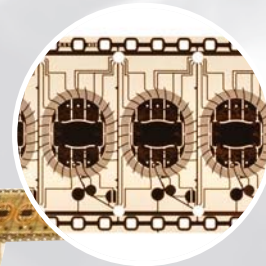
Position Sensors
Motor Drivers
Starters
Intake Manifold
Controllers
TPMS Sensors



- Press-Fit/Compliant Technology
- Wire-bondable Connections
- Tuning Forks and Sockets
- High Temp. Alloys & Plastic Options
- High Current Options
- I/O Connector Options

Micro-Module Packaging Substrates

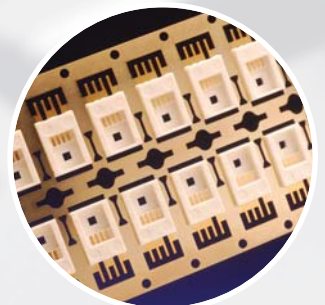
Security Tags
RFID Tags
Smart Cards
Passports
Bank Cards



- Single & Double Layer
- Plated Through Holes
- Flexible & Wire-bondable
- Reeled Format
- Platings Options-Ag, Sn, NiAu, NiPdAu

Continuous Plastic Assemblies and Component Holders

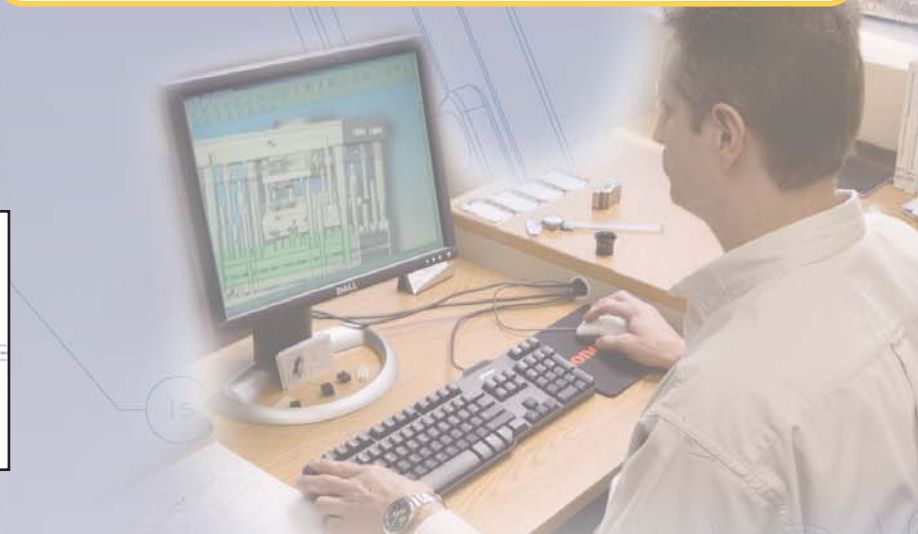
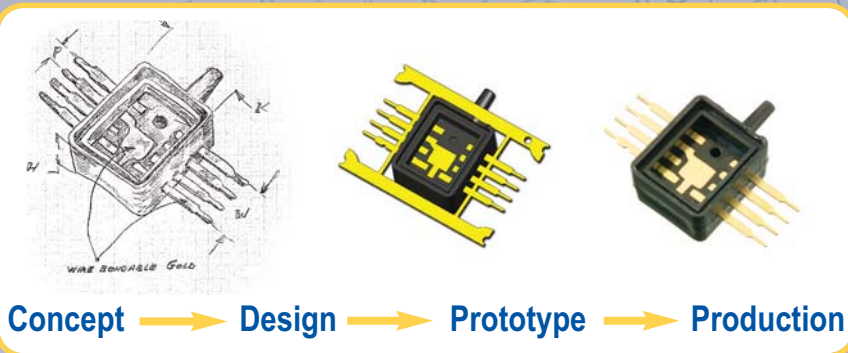
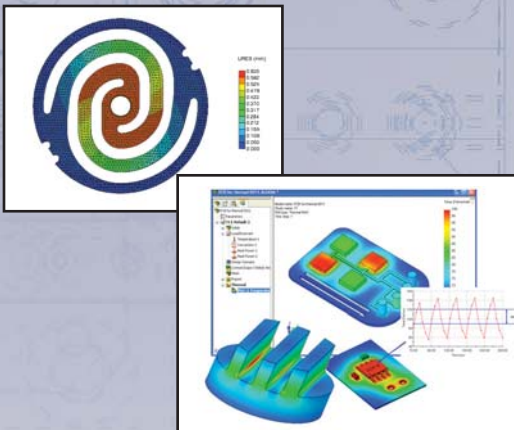
Bobbin Assemblies
Flex Circuit Assemblies
Pressure Sensors
Capacitor Holders
Telecom Jacks
Relays



- Reel to Reel
- SMT or Connector Interface
- Custom & Select Plating Options
- Metal Etched and Stamped Options

Engineering & Development

Application Expertise and Design Assistance
FEA Evaluation
Design Validation & Product Development
Design for Global Manufacturing
Packaging Integration
Production Tool Design and Build
Quick Turn Prototypes



Interplex, a vertically integrated, global manufacturer of small precision parts and assemblies, operates from over 25 worldwide locations in 11 Countries and offers complete solutions from concept through development and into scalable high-volume production for almost any electronic packaging application. Interplex's network of engineers develop solutions that fit the manufacturing needs of our customers and then match up those needs with the best Interplex production facility.

Today, Interplex continues to expand its technologies and capabilities from developing solutions for high-speed data and micropackaging requirements to high-current, thermally efficient packaging for power generation and conversion in applications such as RF Power and Hybrid technologies. Interplex is always driven by the singular mission to deliver innovative solutions and services to our customers.

Over 25 Global Locations in 11 Countries

One Global Resource...

- Precision Stamping
- Complex Molding
- Precision Plating
- Reel to Reel Etching
- Solder Bearing Lead Products
- Press-fit Interconnect Technology
- Automation Development
- Engineering Services
- Manufacturing Development

